

PCN Number:	20191127000.1		PCN Date:	Jan 13, 2020																			
Title:	Qualification of additional Fab site (UMC-F12X) and Assembly site (SCK) options for select devices																						
Customer Contact:	PCN Manager		Dept:	Quality Services																			
Proposed 1st Ship Date:	Apr 13, 2020	Estimated Sample Availability:	Date provided at sample request.																				
Change Type:																							
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials																		
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification																		
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process																		
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process																		
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process																		
		<input type="checkbox"/>	Part number change																				
PCN Details																							
Description of Change:																							
Texas Instruments is pleased to announce the qualification of an additional Fab site (UMC-F12X) and Assembly site (SCK) options for the selected devices listed in the "Product Affected" section.																							
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th colspan="3" style="text-align: center;">Current Fab Site</th> <th colspan="3" style="text-align: center;">Additional Fab Site</th> </tr> <tr> <th style="text-align: center;">Fab Site</th> <th style="text-align: center;">Process</th> <th style="text-align: center;">Wafer Diameter</th> <th style="text-align: center;">Fab Site</th> <th style="text-align: center;">Process</th> <th style="text-align: center;">Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td style="text-align: center;">UMC-F12</td> <td style="text-align: center;">C28</td> <td style="text-align: center;">300 mm</td> <td style="text-align: center;">UMC-F12X</td> <td style="text-align: center;">C28</td> <td style="text-align: center;">300 mm</td> </tr> </tbody> </table>						Current Fab Site			Additional Fab Site			Fab Site	Process	Wafer Diameter	Fab Site	Process	Wafer Diameter	UMC-F12	C28	300 mm	UMC-F12X	C28	300 mm
Current Fab Site			Additional Fab Site																				
Fab Site	Process	Wafer Diameter	Fab Site	Process	Wafer Diameter																		
UMC-F12	C28	300 mm	UMC-F12X	C28	300 mm																		
There are no Assembly material differences between sites.																							
Reason for Change:																							
Continuity of Supply																							
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																							
None																							
Anticipated impact on Material Declaration																							
<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website .																				
Changes to product identification resulting from this PCN:																							
Fab Site Information:																							
Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City																				
UMC-F12	F12	TWN	Tainan																				
UMC-F12X	UCX	CHN	Xiamen																				
Assembly Site Information:																							
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly Site City																				
Amkor K4	AMP	KOR	Gwangju																				
STATS ChipPAC	SCK	KOR	Incheon																				

Sample product shipping label (not actual product label)



MADE IN: Malaysia
2DC: 2Q:



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483S12
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO: USA
(22L) ASO: MLA (23L) ACC: MYS

MSL 2 / 260C / 1 YEAR SEAL DT
MSL 1 / 235C / UNLIM 03/29/04

OPT:
ITEM: 39
LBL: 5A (L) TO: 1750

Product Affected:

AM5716AABCD	AM5716AABCX	AM5716AABCXEA	AM5718AABCXA
AM5716AABCDA	AM5716AABCXA	AM5718AABCX	AM5718AABCXEA
AM5716AABCDEA			

Qualification Report

Approved on 17-Dec-2019

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: 791842BABCQ	QBS Process Reference: X5777BXCABC	QBS Process Reference: X5777BXCABC	QBS Package Reference: X5777BXCABC
HTSL	High Temp Storage Life, 150C	1000 Hours	-	2/154/0	1/77/0	3/231/0
HTOL	High Temp. Operating Life, 125C	1000 Hours	1/77/0	2/154/0	1/77/0	-
LU	Latch-up, 125C	+/-100 mA	1/6/0	-	-	-
CDM	ESD - CDM	250 V	1/3/0	-	-	-
HBM	ESD - HBM	1000 V	1/3/0	1/3/0	-	-
TC	Temperature Cycle, -55/125C	1000 Cycles	-	2/154/0	1/77/0	3/231/0
THB	Biased Temperature and Humidity, 85C/85%RH	1000 Hours	-	2/154/0	1/77/0	3/231/0
UHAST	Unbiased HAST, 110C/85%RH	264 Hours	-	2/154/0	1/77/0	3/231/0

- QBS: Qual By Similarity

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

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